

PATENT ASSIGNMENT COVER SHEET

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Assignment ID: PATI465375

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Jean-Luc Dubois	08/20/2024
RECEIVING PARTY DATA	
Company Name:	Arkema France
Street Address:	420 rue d'Estienne d'Orves
City:	Colombes
State/Country:	FRANCE
Postal Code:	92700
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17049725
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NAME OF SUBMITTER:	Joan Bice
SIGNATURE:	Joan Bice
DATE SIGNED:	08/30/2024
Total Attachments: 2	
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source=AM 4098-US-PCT-20240830-R-Assignment signed#page2.tiff	

ASSIGNMENT

As the below named inventor, I hereby declare that this Assignment is directed to:

- (1) ☒ U.S. application number 17/049,725, filed on October 22, 2020, entitled METHOD FOR RECYCLING THERMOPLASTIC BY SHORT DEPOLYMERISATION; or
- (2) ☐ ~~the attached application entitled LIQUID COMPOSITION FOR APPLICATIONS OF SMC MOULDED THERMOPLASTIC COMPOSITES.~~

THIS ASSIGNMENT, by the undersigned inventor (hereinafter referred to as "the Assignor"), respectively, witnesseth:

WHEREAS, the Assignor has invented certain new and useful improvements set forth in an application for Letters Patent of the United States, which is a nonprovisional application;

WHEREAS, ARKEMA FRANCE, a corporation duly organized under and pursuant to the laws of France and having a principal place of business at 420 rue d'Estienne d'Orves, Colombes, 92700 France (hereinafter referred to as "the Assignee"), is desirous of acquiring the entire right, title, and interest in and to said inventions, the right to file applications on said inventions and the entire right, title and interest in and to any applications, including provisional applications for Letters Patent of the United States or other countries claiming priority to said application, and in and to any Letters Patent or Patents, United States or foreign, to be obtained therefor and thereon.

NOW, THEREFORE, for good and sufficient consideration, the receipt of which is hereby acknowledged, the Assignors have ~~sole~~ assigned, transferred, and set over, and by these presents do ~~self~~ assign, transfer, and set over, unto the Assignee, its successors, legal representatives, and assigns the entire right, title, and interest in and to the above-mentioned inventions, the right to file applications on said inventions and the entire right, title and interest in and to any applications for Letters Patent of the United States or other countries claiming priority to said applications, and any and all Letters Patent or Patents of the United States of America and all foreign countries that may be granted therefor and thereon, and in and to any and all applications claiming priority to said applications, divisions, continuations, and continuations-in-part of said applications, and reissues and extensions of said Letters Patent or Patents, and all rights under the International Convention for the Protection of Industrial Property, the same to be held and enjoyed by the Assignee, for its own use and behoof and the use and behoof of its successors, legal representatives, and assigns, to the full end of the term or terms for which Letters Patent or Patents may be granted as fully and entirely as the same would have been held and enjoyed by the Assignors had this sale and assignment not been made;

AND for the same consideration, the Assignors hereby covenant and agree to and with the Assignee, its successors, legal representatives, and assigns, that, at the time of execution and delivery of these presents, the Assignors are the sole and lawful owners of the entire right, title, and interest in and to the inventions set forth in said applications and said applications, including provisional applications, above-mentioned, and that the same are unencumbered, and that the Assignors have good and full right and lawful authority to sell and convey the same in the manner herein set forth;

AND for the same consideration, the Assignors hereby covenant and agree to and with the Assignee, its successors, legal representatives, and assigns that the Assignors will, whenever counsel of the Assignee, or the counsel of its successors, legal representatives, and assigns, shall advise that any proceeding in connection with said inventions or said applications for Letters Patent or Patents, or any proceeding in connection with Letters Patent or Patents for said inventions in any country, including interference proceedings, is lawful and desirable, or that any application claiming priority to said application, division, continuation, or continuation-in-part of any applications for Letters Patent or Patents, or any reissue or extension of any Letters Patent or Patents to be obtained thereon, is lawful and desirable, sign all papers and documents, take all lawful oaths, and do all acts necessary or required to be done for the procurement, maintenance, enforcement, and defense of Letters Patent

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^{Assignor}
or Patents for said inventions, without charge to the ~~Assignee~~, its successors, legal representatives, and assigns,
but at the cost and expense of the Assignee, its successors, legal representatives, and assigns;

AND the Assignors hereby request the Commissioner of Patents to issue any and all said Letters Patent
of the United States to the Assignee as the Assignee of said inventions, the Letters Patent to be issued for the
sole use and behoof of the Assignee, its successors, legal representatives, and assigns.

August 20th 2024
Date

Jean-Luc DUBOIS

Name



Signature
Jean-Luc DUBOIS

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